

## T-1 (3mm) SOLID STATE LAMP

Part Number: L-7104GD-5V

Green

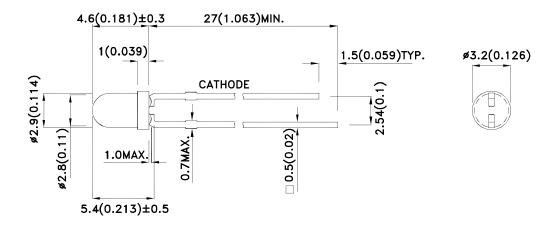
#### **Features**

- Low power consumption.
- Popular T-1 diameter package.
- General purpose leads.
- Reliable and rugged.
- Long life solid state reliability.
- Available on tape and reel.
- 5V internal resistor.
- RoHS compliant.

### Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

## **Package Dimensions**



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SPEC NO: DSAE8438 **REV NO: V.5** DATE: SEP/03/2010 PAGE: 1 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: C.H.HAN ERP: 1101029206





### **Selection Guide**

Part No.	Dice Lens Type Iv (mcd) [2]			Viewing Angle [1]	
		2.	Min.	Тур.	201/2
L-7104GD-5V	Green (GaP)	GREEN DIFFUSED	12	25	40°

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

# Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	565		nm	V <sub>F</sub> =5V
λD [1]	Dominant Wavelength	Green	568		nm	V <sub>F</sub> =5V
Δλ1/2	Spectral Line Half-width	Green	30		nm	V <sub>F</sub> =5V
lF	Forward Current	Green	11.5	17.5	mA	VF=5V
lr	Reverse Current	Green		10	uA	VR = 5V

1.Wavelength: +/-1nm.

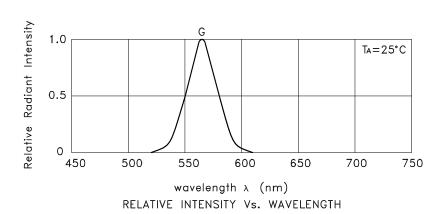
## Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units	
Power dissipation	85	mW	
Forward Voltage	6	V	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +70°C		
Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [1]	260°C For 3 Seconds		
Lead Solder Temperature [2]	260°C For 5 Seconds		

### Notes:

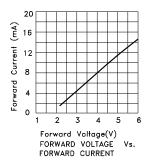
- 2mm below package base.
   5mm below package base.

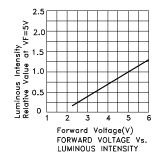
SPEC NO: DSAE8438 **REV NO: V.5** DATE: SEP/03/2010 PAGE: 2 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: C.H.HAN ERP: 1101029206

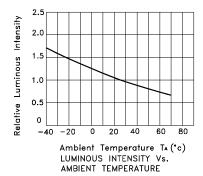


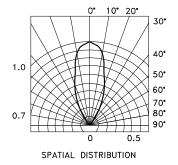
Green

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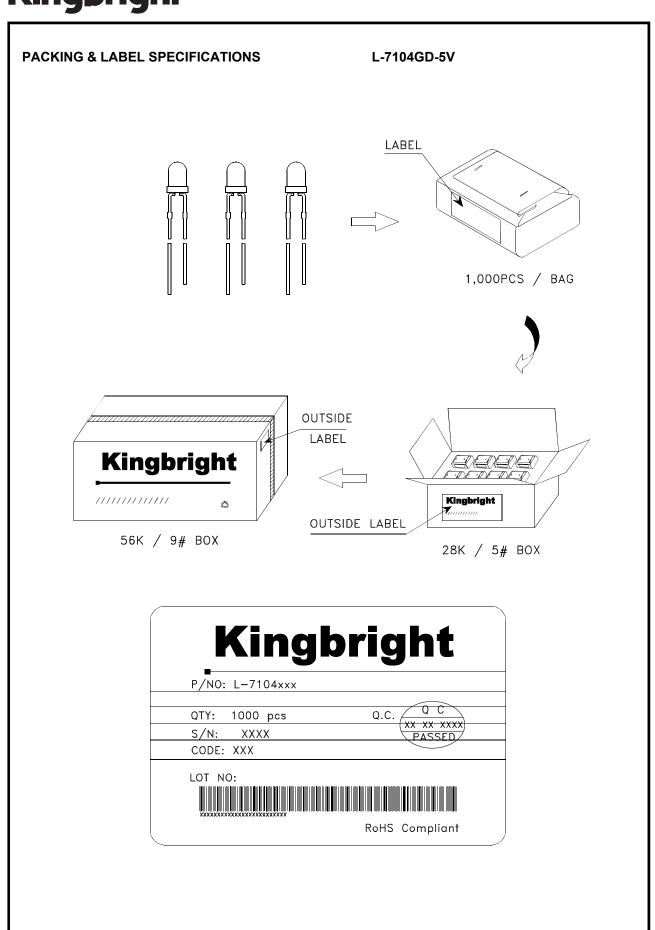








SPEC NO: DSAE8438 APPROVED: WYNEC REV NO: V.5 CHECKED: Allen Liu DATE: SEP/03/2010 DRAWN: C.H.HAN PAGE: 3 OF 6 ERP: 1101029206

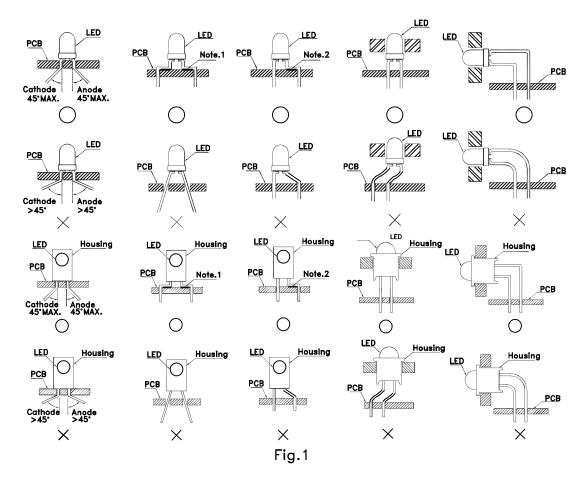


SPEC NO: DSAE8438 APPROVED: WYNEC REV NO: V.5 CHECKED: Allen Liu DATE: SEP/03/2010 DRAWN: C.H.HAN PAGE: 4 OF 6 ERP: 1101029206

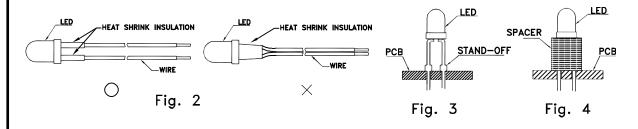
### LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

(Fig. 1)



- "O" Correct mounting method "X" Incorrect mounting method Note 1-2: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.
- 2. When soldering wire to the LED, use individual heat—shrink tubing to insulate the exposed leads to prevent accidental contact short—circuit. (Fig. 2)
- 3. Use stand—offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.

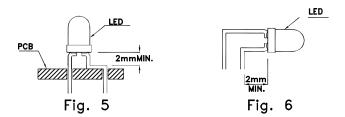


 SPEC NO: DSAE8438
 REV NO: V.5
 DATE: SEP/03/2010
 PAGE: 5 OF 6

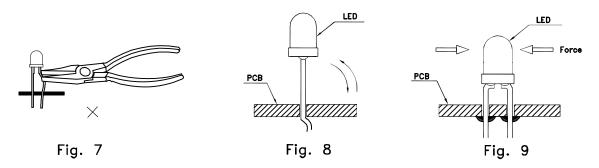
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### LEAD FORMING PROCEDURES

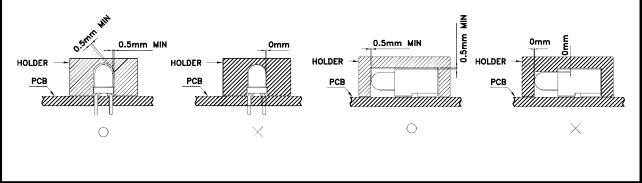
1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)



- 2. Lead forming or bending must be performed before soldering, never during or after Soldering.
- 3. Do not stress the LED lens during lead—forming in order to fractures in the lens epoxy and damage the internal structures.
- 4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
- 5. Do not bend the leads more than twice. (Fig. 8)
- 6. After soldering or other high—temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.



7. No stress shall be applied on the LED during soldering to prevent damage.



SPEC NO: DSAE8438 APPROVED: WYNEC REV NO: V.5 CHECKED: Allen Liu DATE: SEP/03/2010 DRAWN: C.H.HAN PAGE: 6 OF 6 ERP: 1101029206